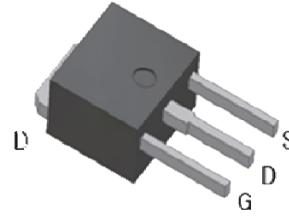
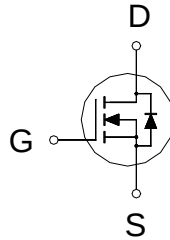


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	500V
$R_{DS(on)} (MAX.)$	1.85Ω
I_D	5A



UIS, 100% Tested

Pb-Free Lead Plating



ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	5	A
	$T_C = 100^\circ\text{C}$		3	
Pulsed Drain Current ¹		I_{DM}	20	
Avalanche Current		I_{AS}	5	mJ
Avalanche Energy	$L = 3\text{mH}, I_D = 5\text{A}, R_G = 25 \Omega$	E_{AS}	37.5	
Repetitive Avalanche Energy ²	$L = 0.5\text{mH}$	E_{AR}	6.25	
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	48	W
	$T_C = 100^\circ\text{C}$		19	
Operating Junction & Storage Temperature Range		$T_{j, T_{stg}}$	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		2.6	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

ELECTRICAL CHARACTERISTICS ($T_c = 25\text{ }^{\circ}\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	500			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500V, V_{GS} = 0V$			10	μA
		$V_{DS} = 400V, V_{GS} = 0V, T_J = 125\text{ }^{\circ}C$			25	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 2.5A$		1.55	1.85	Ω
Forward Transconductance ¹	g_{fs}	$V_{DS} = 25V, I_D = 2.5A$		5		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		469		pF
Output Capacitance	C_{oss}			49		
Reverse Transfer Capacitance	C_{rss}			2.6		
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = 250V, V_{GS} = 15V, I_D = 2.5A$		8.5		nC
Gate-Source Charge ^{1,2}	Q_{gs}			2.2		
Gate-Drain Charge ^{1,2}	Q_{gd}			2.3		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = 250V, I_D = 2.5A, V_{GS} = 15V, R_{GS} = 10\Omega$		9		nS
Rise Time ^{1,2}	t_r			10		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			25		
Fall Time ^{1,2}	t_f			8		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T _c = 25 °C)						
Continuous Current	I _S				5	A
Pulsed Current ³	I _{SM}				20	
Forward Voltage ¹	V _{SD}	I _F = I _S , V _{GS} = 0V			1.5	V
Reverse Recovery Time	t _{rr}	I _F = I _S , dI _F /dt = 100A / μS		0.6		μS
Reverse Recovery Charge	Q _{rr}			32		nC

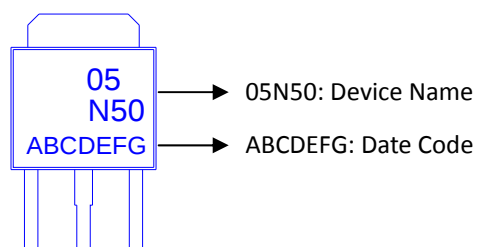
¹Pulse test : Pulse Width $\leq 300\text{ }\mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

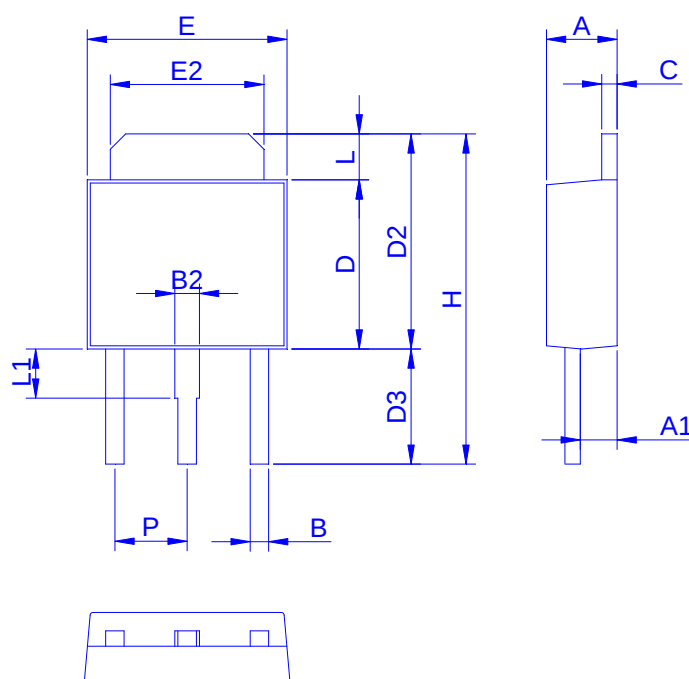
³Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMD05N50 CS for IPAK (TO-251)



Outline Drawing



Dimension in mm

Dimension	A	A1	B	B2	C	D	D2	D3	E	E2	H	L	L1	P
Min.	2.10	0.90	0.40	0.60	0.40	5.30	6.70	3.40	6.30	4.80	10.2	0.89	0.90	2.10
Max.	2.50	1.50	0.90	1.15	0.60	6.25	7.30	4.30	6.80	5.50	11.5	1.40	1.80	2.50

TYPICAL CHARACTERISTICS

